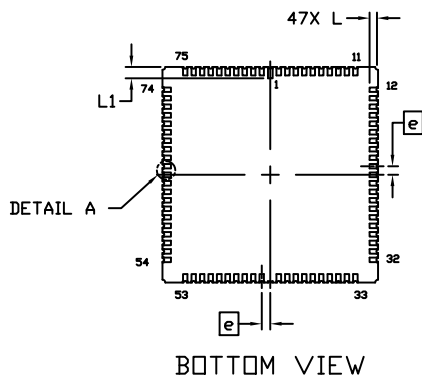
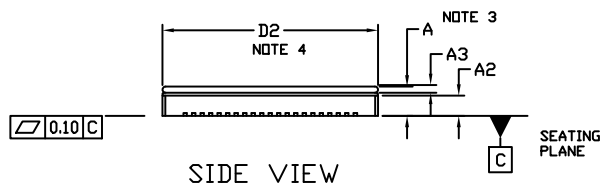
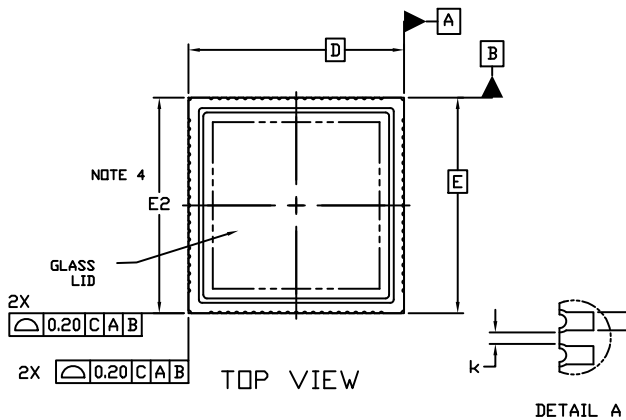


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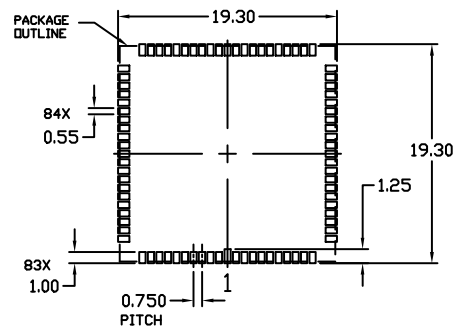
DATE 26 JUN 2015



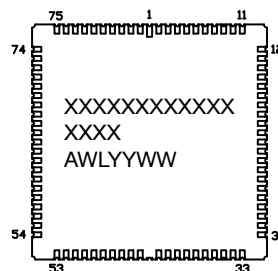
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER ATTACHED FEATURES.
4. THE LID IS DEFINED BY DIMENSIONS D2 AND E2 AND HAS A MAXIMUM ALLOWABLE SHIFT OF 0.60 BEYOND DIMENSIONS D AND E.

DIM	MILLIMETERS	
	MIN.	MAX.
A	2.08	2.74
A2	1.78	REF
A3	0.55	REF
b	0.32	0.48
D	19.00	BSC
D2	19.00	REF
E	19.00	BSC
E2	19.00	REF
e	0.75	BSC
k	0.12	---
L	0.62	0.88
L1	1.00	REF



GENERIC MARKING DIAGRAM



- XXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week

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